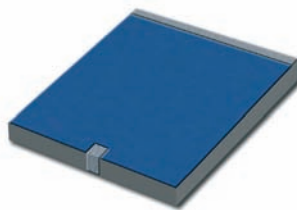
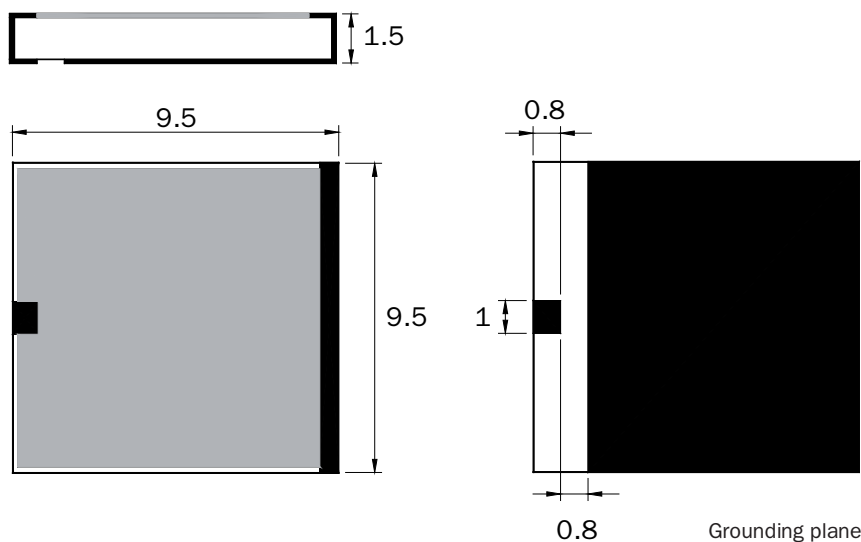
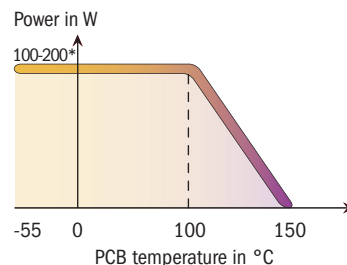


Standards
NF C 96-315
MIL-DTL-39030



| | |
|-------------------|-------------------------|
| Substrate | AIN |
| Resistive film | Thick film |
| Protection film | Epoxy |
| Contacts finition | Tin over Nickel barrier |



Dimensions in mm

| P/N | Frequency (GHz) | Power (W) | Impedance ($\Omega \pm 5\%$) | Max VSWR |
|----------|-----------------|-----------|--------------------------------|----------|
| 45-0025S | 3.5 | 200 | 50 | 1.30 |

| mm | inch |
|-----|-------|
| 0.8 | 0.031 |
| 1 | 0.039 |
| 1.5 | 0.059 |
| 9.5 | 0.374 |

*** IMPORTANT NOTE FOR POWER DISSIPATION**

100 W : When mounted on PCB 0.8 mm thick Sn 35 μ plated with 120 via holes \varnothing 0.5 mm filled with Sn96Ag4 solder.
200 W : When directly soldered on \varnothing 6.35 mm Cu cylinder acting as a thermal drain.

Available on Tap and Reel Packaging